

Fig. 1

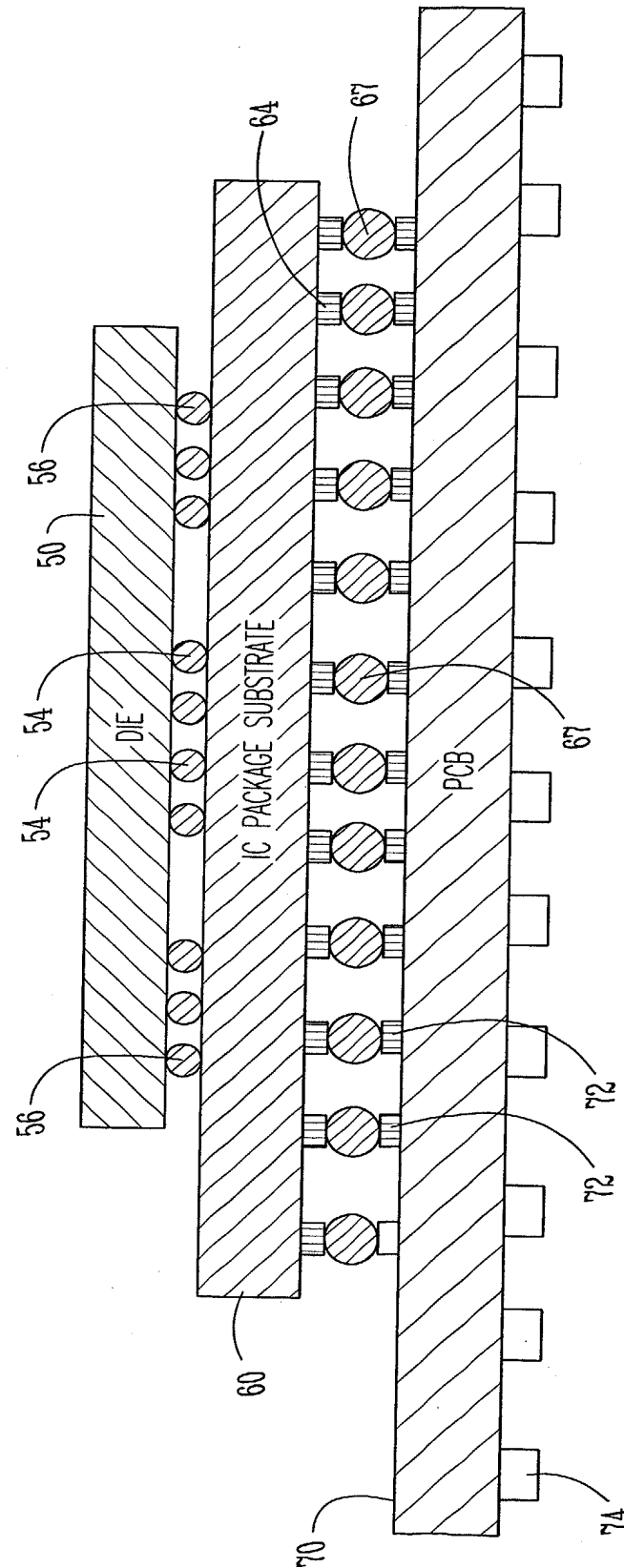


Fig. 2
(Prior Art)

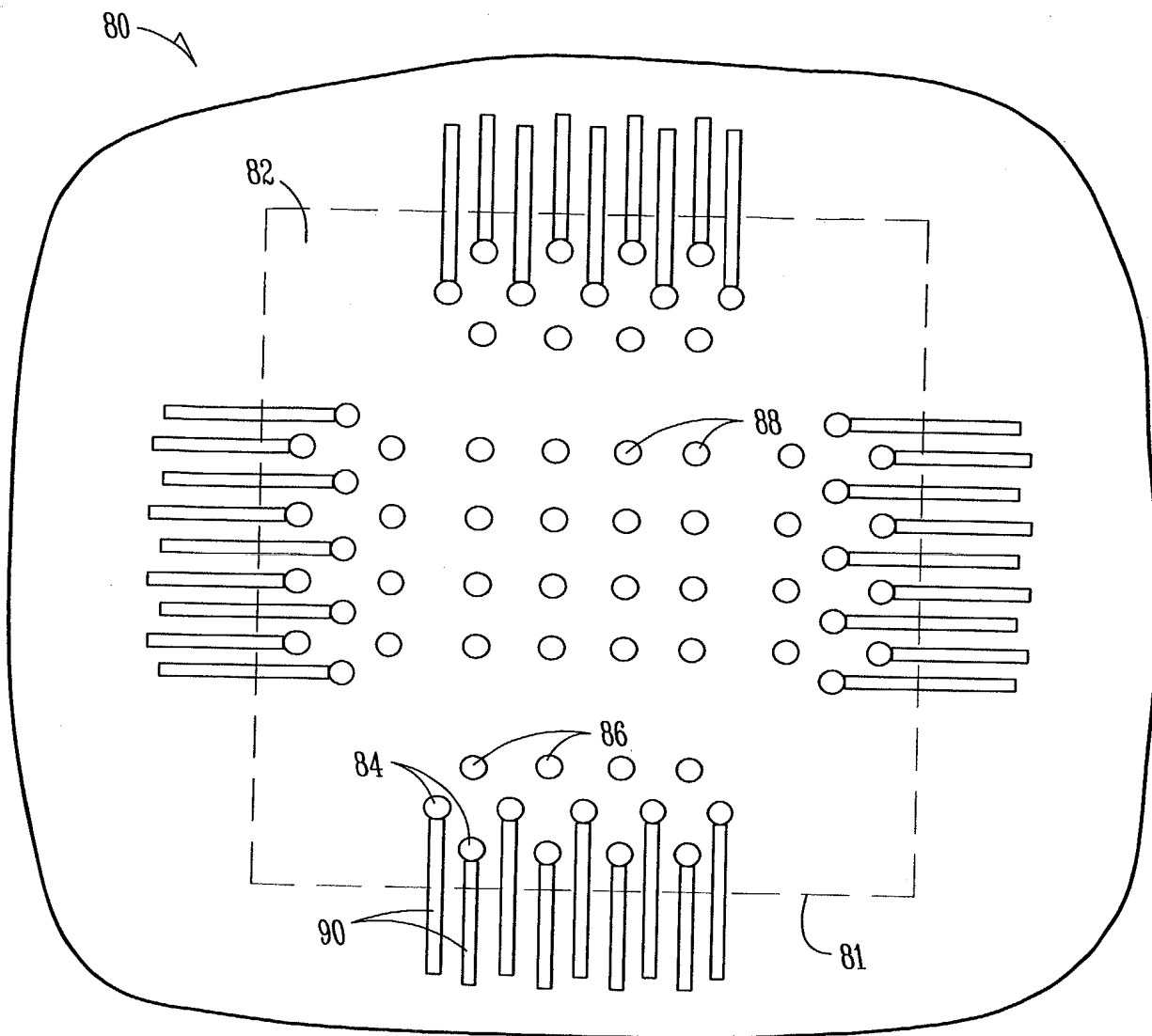


Fig. 3
(Prior Art)

09533-054604

APPROVED	O.G. FIG.	TITLE:
BY	CLASS	SUBCLASS
DRAFTSMAN		

ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED METHODS
 INVENTORS NAME: Tee Onn Chong et al.
 DOCKET NO.: 884.419US1

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100

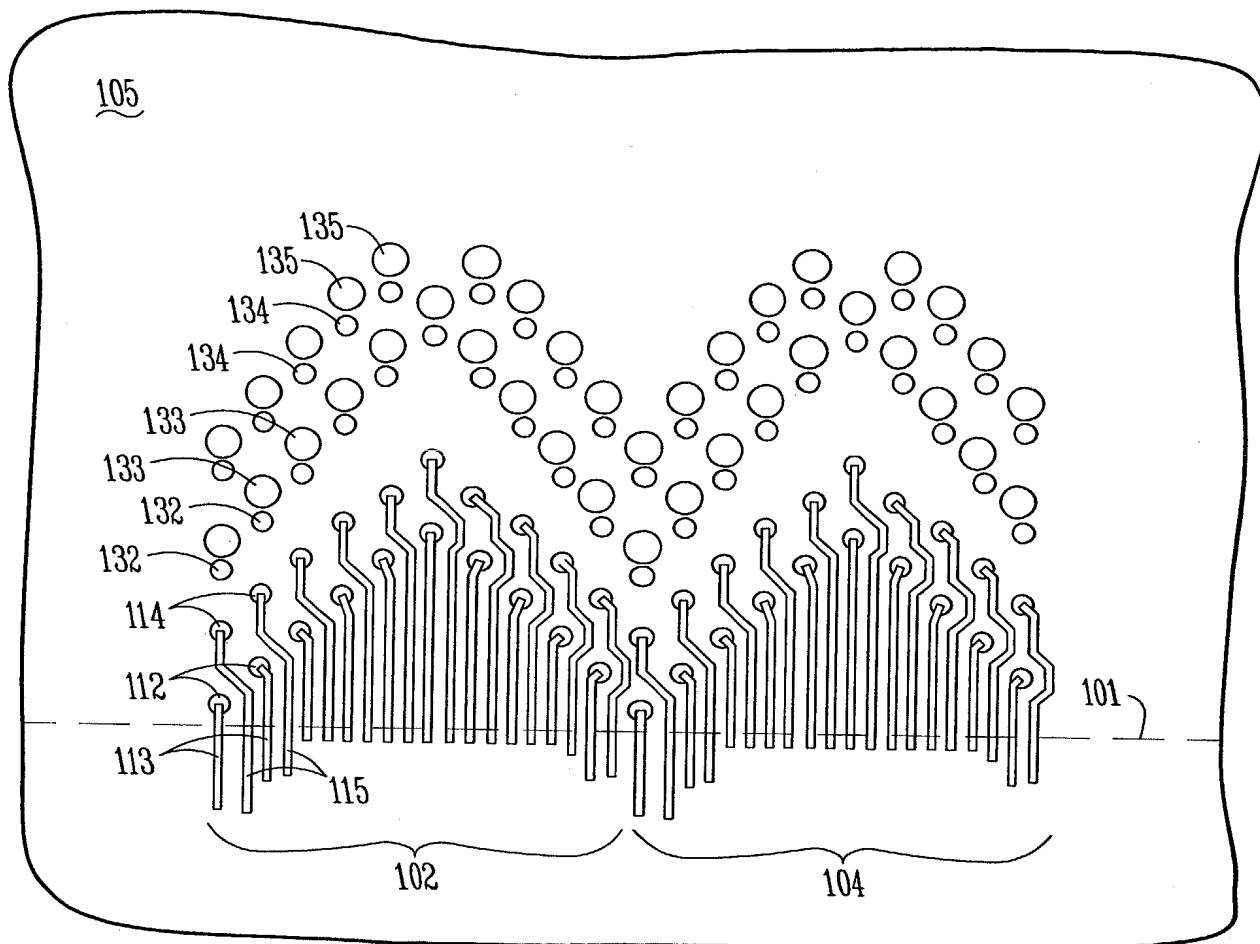


Fig. 4

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150

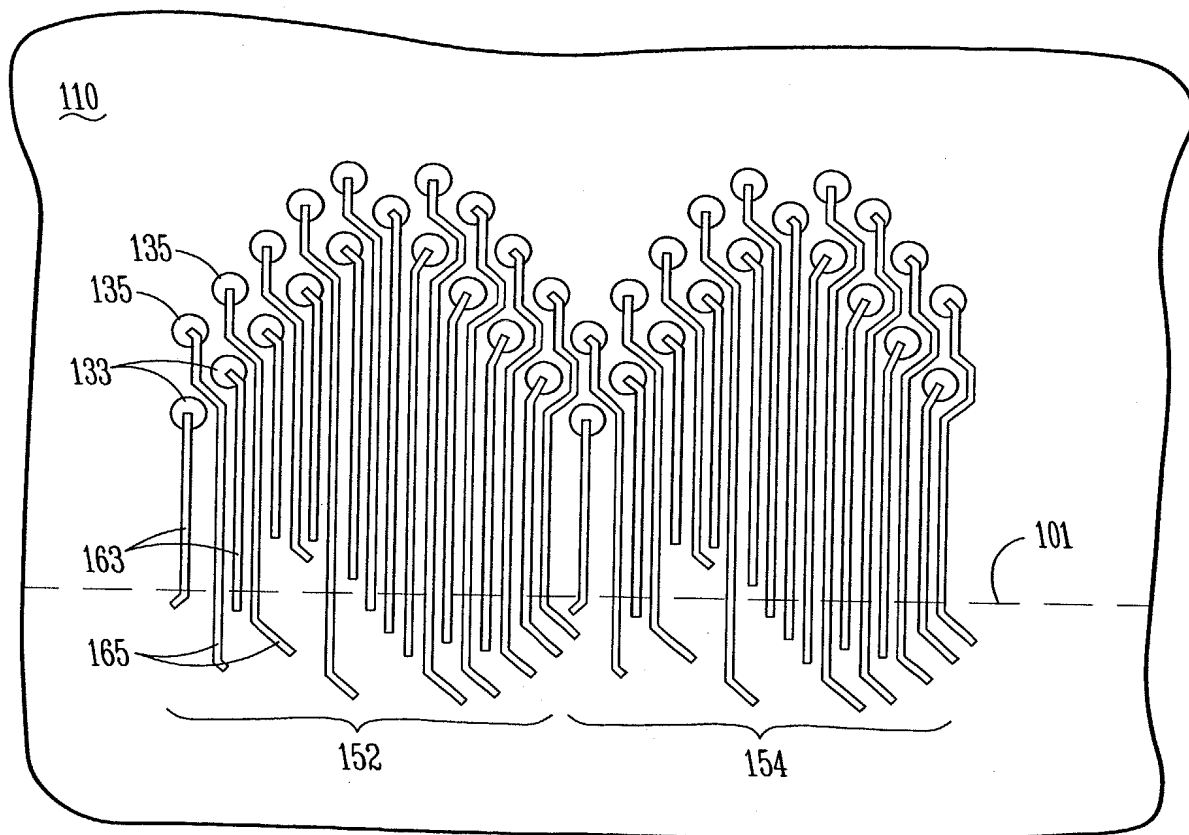


Fig. 5

0958230 051401
 105150" 88285860

APPROVED	O. G. FIG.	TITLE:
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CRAFTSMAN		

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200

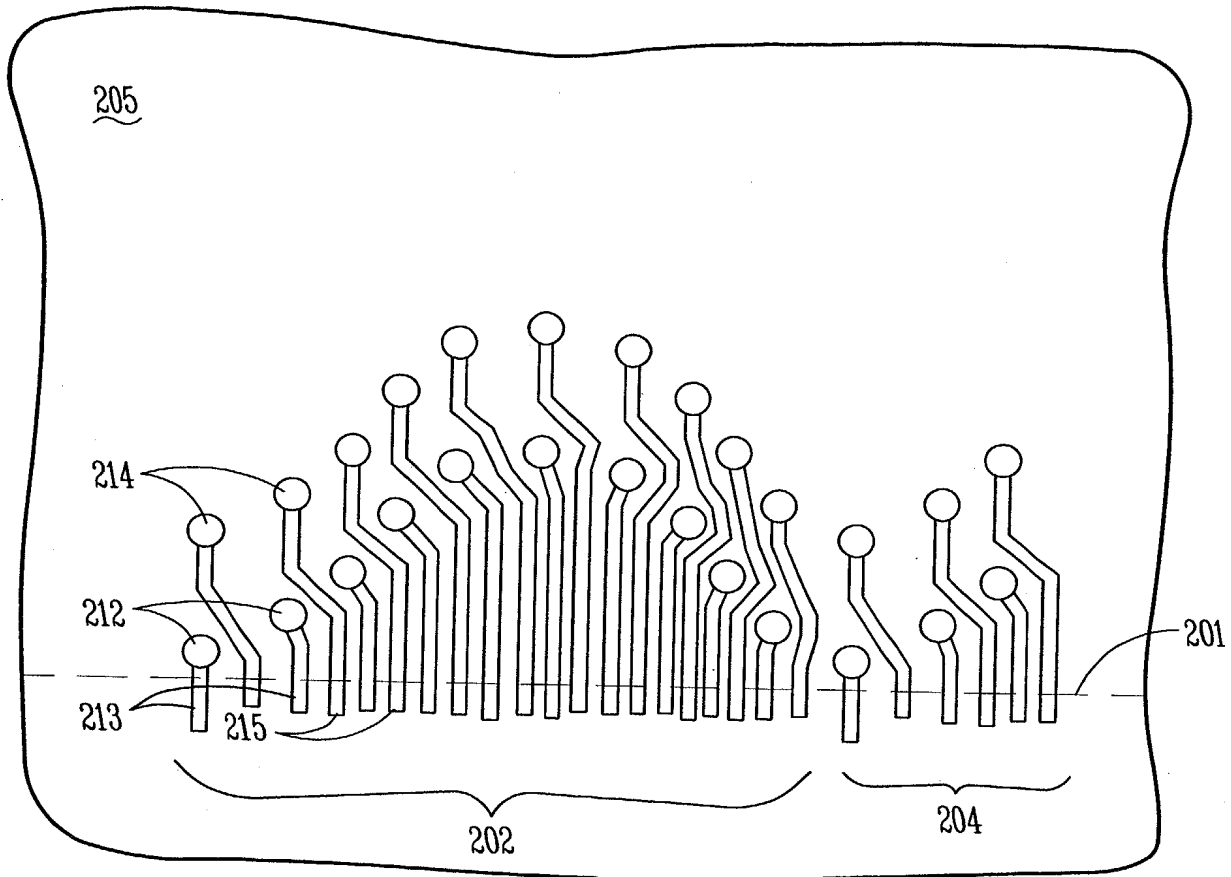


Fig. 6

0958230 051504

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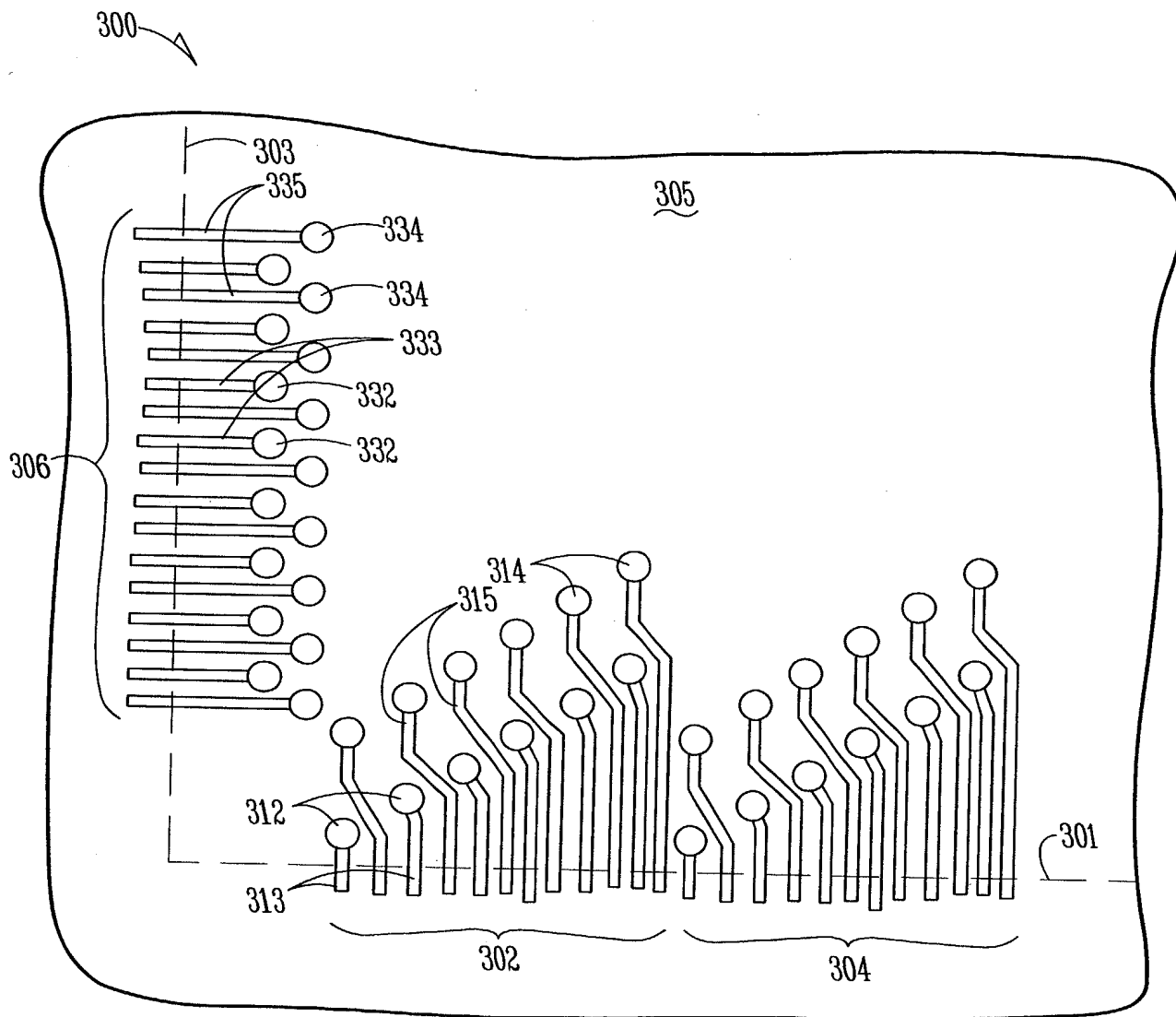


Fig. 7

350 ↗

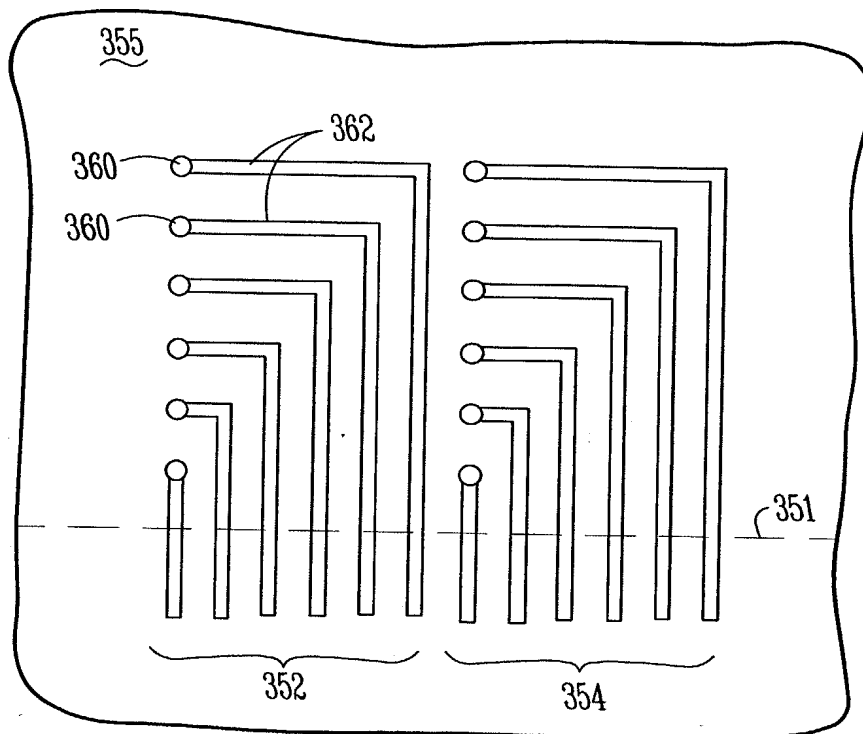


Fig. 8

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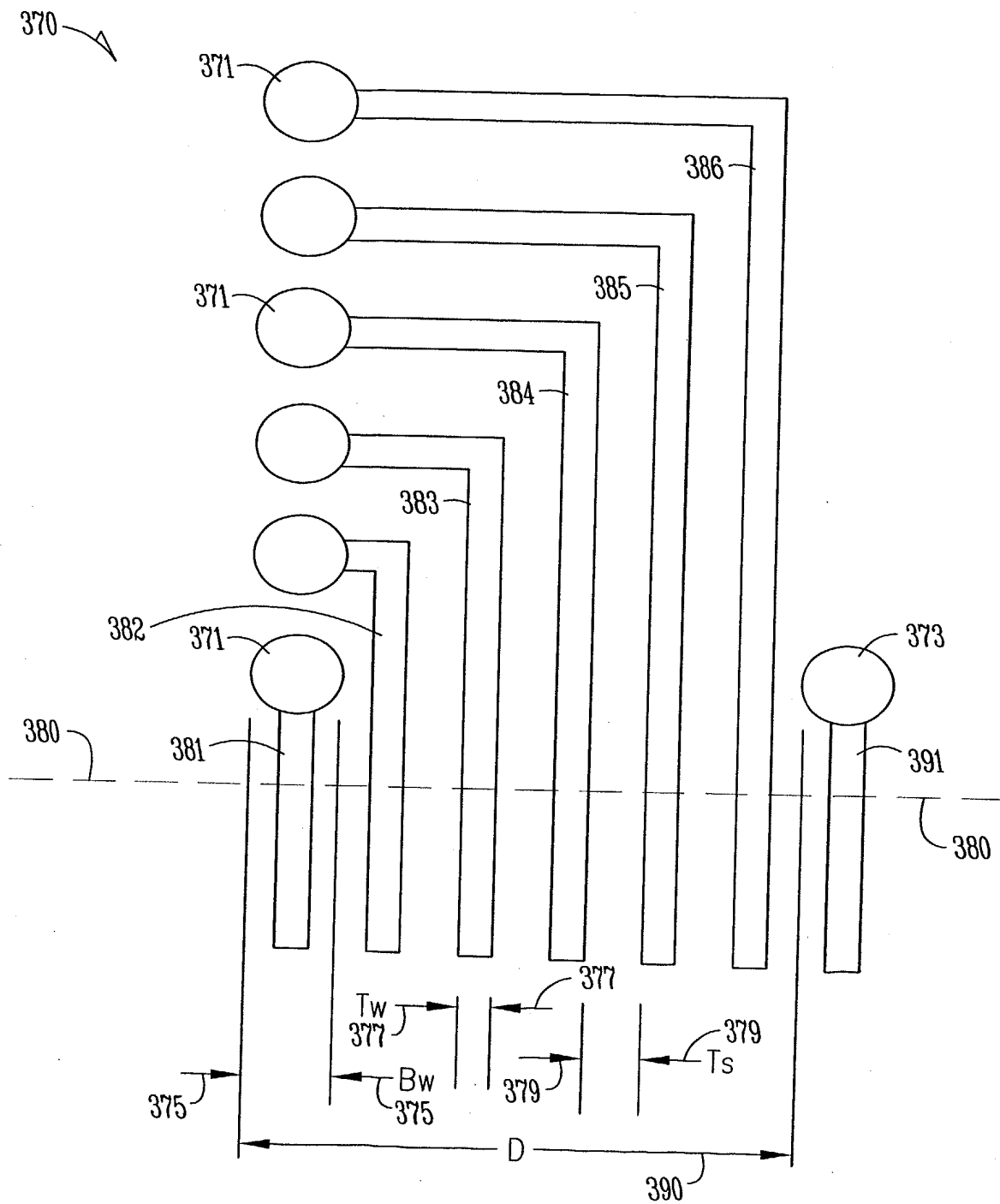


Fig. 9

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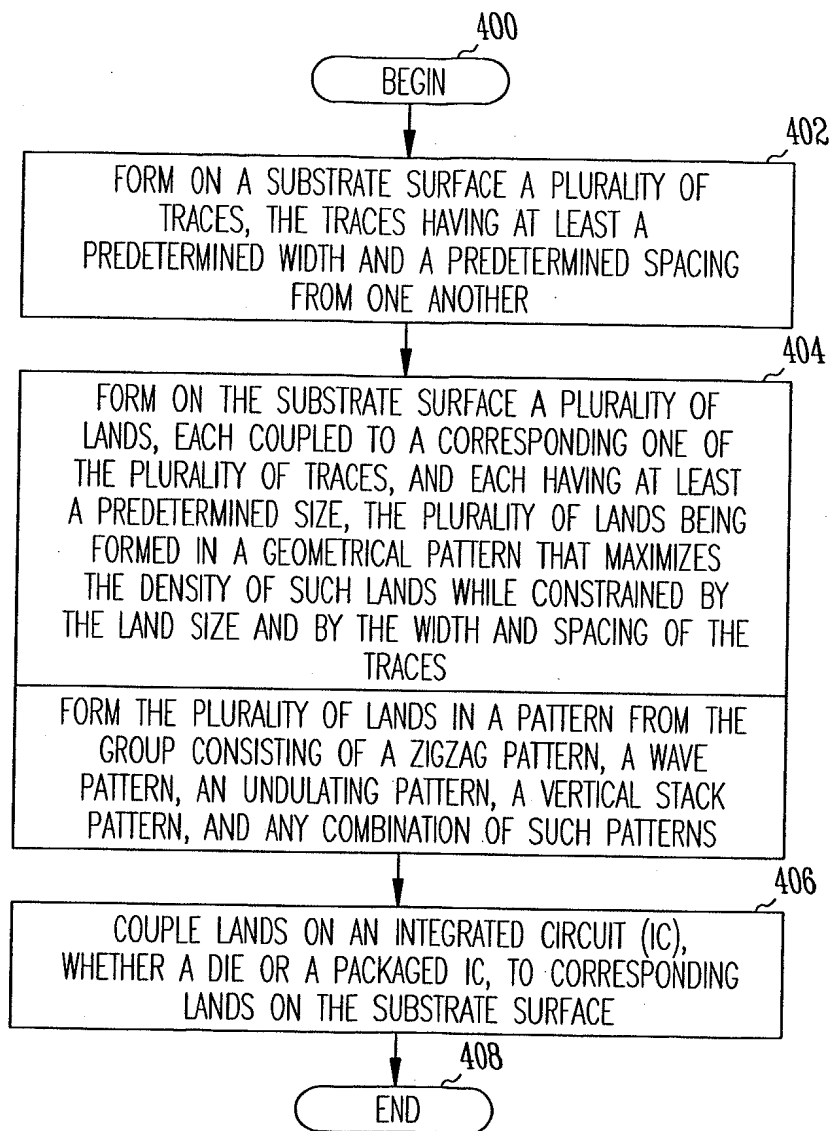


Fig. 10

0058238-051501

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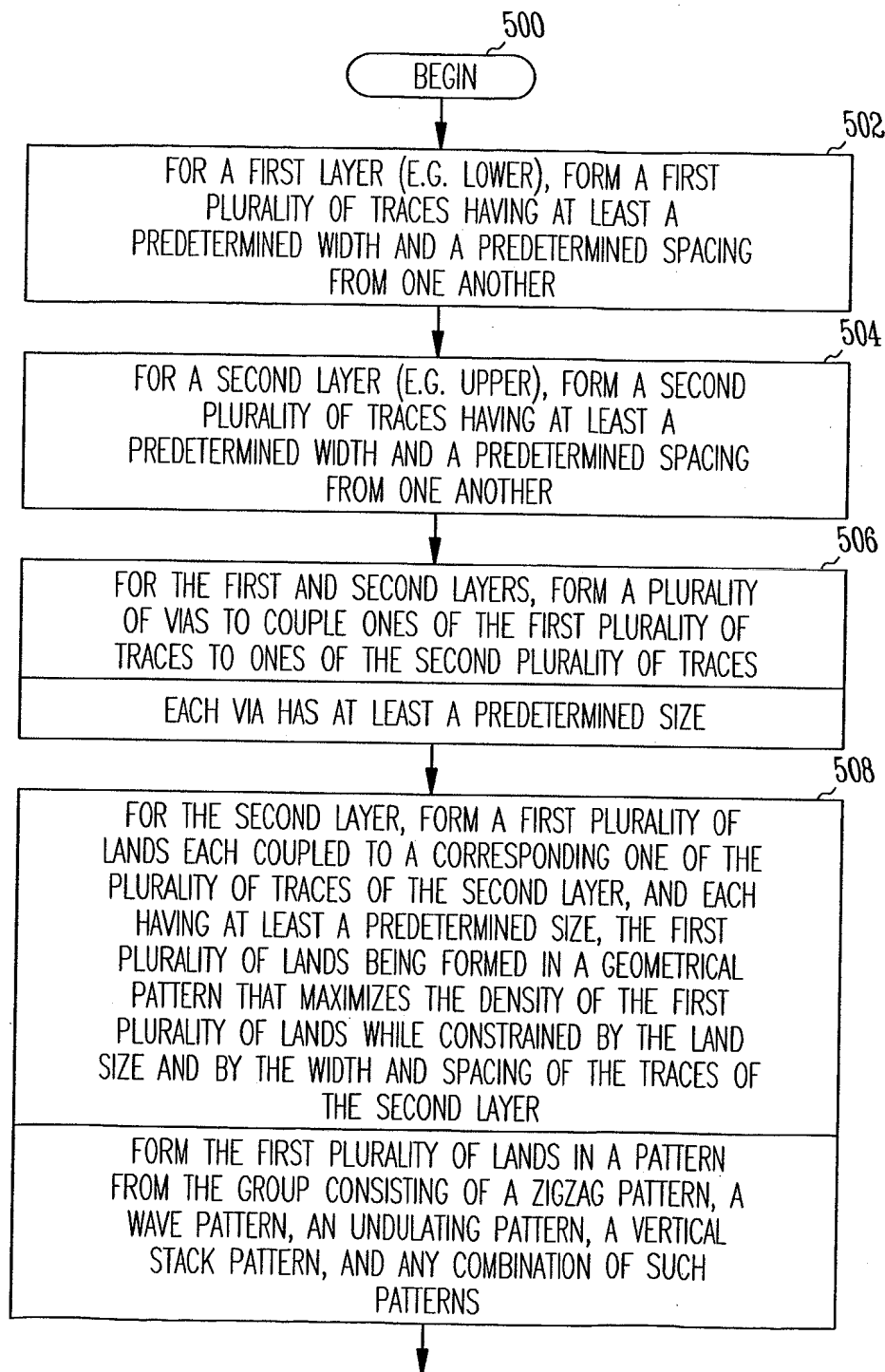


Fig. 11A

0958338-05101

APPROVED	C.G. FIG.	TITLE:
BY	CLASS	SUBCLASS
DRAFTSMAN		

ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED METHODS
INVENTORS NAME: Tee Onn Chong et al.
DOCKET NO.: 884.419US1

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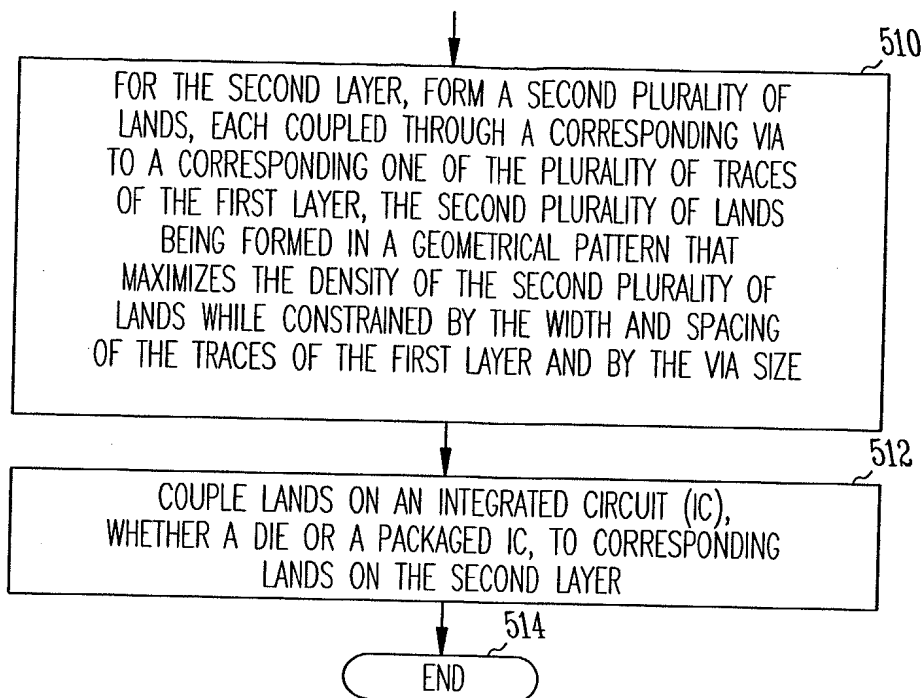


Fig. 11B

09858238-051501